L Number	Hits	Search Text	DB	Time stamp
1	126	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/07 10:01
2	0	438/14,15,762,763.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/07 10:02
3	32	(integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) and (lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/07 10:03
-	6039	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/30 15:08
-	0	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bomds)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/30 15:10
-	184	(integrated adj circuit) and (contact or output/input adj pads) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/30 15:15
-	118	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 10:15
-	118	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 10:25
-	0	"09888674" and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 15:37
-	0	"09888674" and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/20 10:14
-	0	"09/888674" and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 11:45
-	118	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/07 09:59
-	0	(integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder adj bonds) and (wire adj bonds) and (barrier) and (passivation)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 12:24
-	0	(integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder adj bonds) and (wire adj bonds) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 12:25
-	4	(integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire adj bonds) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 12:26
-	28	(integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/01 15:10

-	118	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 15:38
-	23	(integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) and (lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/07 10:03
-	0	438/15.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 18:38
-	0	438/15,762,763.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/07 10:01
-	4	257/737.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 18:41
-	27	(integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) and (lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 18:01
-	0	438/15.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 18:44
-	123	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 18:41
-	4	257/737.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 18:51
-	0	438/15.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 18:45
-	8	257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 19:03
-	4	257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/30 19:04
-	36	(integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/31 11:42
-	4	(integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/31 11:43
-	0	"6221682" and gold	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 13:21
-	0	"20010011764" and gold	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 13:52
-	2	"20010011764"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 13:52

–	0	"6441487" and (gold)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 15:37
–	9	"5234149" and (gold)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 15:38
–	6	"5234149" and (under adj bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 19:18
–	0	5234149.pn. and (under adj bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 17:48
–	1	"20010011764" and (under adj bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 19:18
–	1	"20010011764" and (electroplating)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 19:19
–	10	"5234149" and (reflow$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/20 10:15
–	0	5234149.pn. and (reflow$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/20 10:16
–	1	20010011764.pn. and (reflow$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/20 10:31
–	1	20010011764.pn. and (lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/20 10:34
–	1	20010011764.pn. and (reflow$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/20 11:05
–	0	20010011764.pn. and (selective adj electroplating)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/20 11:05